



**Meetings Quick Reference List**  
(as of 11 July 2007)

**I. MEETINGS FOR WHICH EDS ALWAYS PROVIDES SPONSORSHIP OR CO-SPONSORSHIP SUPPORT (Active Count = 13)**

MEETING NAME/ACRONYM	FREQUENCY/ LAST ATTENDANCE	NEXT OCCURRENCE(S)	EDS FINANCIAL SPONSORSHIP %	CO-SPONSOR(S) & FINANCIAL %
IEEE/SEMI <b>Advanced</b> Semiconductor Manufacturing Conference and Workshop (ASMC)	Annual/06 = 300	June 2008 - USA 2009 - Europe	25%	EDS (25%) CPMITS (25%) SEMI (50%)
IEEE <b>Compound</b> Semiconductor IC Symposium (CSICS) (formerly- IEEE Gallium Arsenide Integrated Circuits Symposium (GaAs IC))	Annual/06 = 272	Oct. 2008 - USA	100%	1993-2000-IEEE MITS (10%)
IEEE International <b>Electron</b> Devices Meeting (IEDM)	Annual/06 = 1,900	12/10-12/07 - D.C. 12/15-17/08 - San Fran.	100%	N/A
IEEE International <b>Integrated</b> Reliability Workshop (IRW) (formerly - Wafer Level Reliability Workshop)	Annual/06 = 120	10/18-21/07	50%	1991 - WLRWS (90%), Tech. Assoc. (10%) 1992-Present - IEEE RS (50%)
IEEE International <b>Interconnect</b> Technology Conference (IITC)	Annual/06 = 650	June 2008	100%	N/A
International Conference on <b>Microelectronics</b> (MIEL)  (Chapter Meeting)	Biennial/06 = 120	5/11-14/08	25%	1995 - Serbian Society for Microelectronics and Optoelectronics (50%), Serbian Council for Science & Technology (20%), University of NIS (Faculty Electrical Engineering (30%) 1997 - Univ. of Elec. Engrg. (Univ. of Nis) (60%) Serbia Ministry of Sci & Tech (20%) Yugoslav Ministry of Sci & Tech (20%) 2000-Present - Faculty of Elec. Eng., Univ. of Nis (60%), Ministries of Sci & Tech. (10%), IEEE Yugoslavia Section (3.5%), IEEE ED/SSC Yugoslavia Chapter (1.5%)
IEEE <b>Non-Volatile</b> Semiconductor Memory Workshop (NVSM) (Starting in 2008, meeting started to rotate locations between USA and Europe, changed frequency to annual from every 18 months and will co-locate with the International Conference on Memory Technology and Design - ICMTD)	Annual/07 = 250	8/26-30/07 USA 5/18-21/08 Europe	100% 100%	N/A N/A
IEEE <b>Photovoltaic</b> Specialists Conference (PVSC)	Every 18 months/05 = 400	5/11-16/08	100%	N/A
IEEE International Symposium on <b>Plasma &amp; Process-Induced Damage</b> (P2ID)	Annual/03 = 56	Conference terminated in 2003	100%	N/A
*IEEE International Conference on <b>Portable</b> Information Devices	Annual/07 = 150	August 2008	20%	2007 - IEEE CPMTS, NTDC, BTS & ComSoc (20% each)
IEEE International <b>Reliability</b> Physics Symposium (IRPS)	Annual/06 = 625	Apr 2008	50%	IEEE RS (50%)
International <b>Semiconductor</b> Conference (CAS)  (Chapter Meeting)	Annual/06 = 130	10/3-5/07	20%	1994 - ICCE of Romania, Ministry of Research and Tech. of Romania 1995 & 96 - ICCE, IEEE Romania Section, SOROS Foundation, Romanian Ministry of Research & Tech.(80%) 1998 - Romanian Ministry of Res. & Tech. (20%), SOROS Foundation (10%), IMT (50%) 1999 - Romanian Ministry of IMT (60%), Res. & Tech. (20%) 2000 - Present - IMT (70%), ANSTI (10%)
IEEE <b>Semiconductor</b> Interface Specialists Conference (SISC)	Annual/06 =104	12/11-13/07	100%	N/A
IEEE International <b>SOI</b> Conference (No std. acronym)	Annual/06 = 170	10/1-4/07	100%	N/A



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(as of 11 July 2007)

**II. MEETINGS FOR WHICH EDS ALTERNATES SUPPORT BETWEEN 'SPONSORSHIP/CO-SPONSORSHIP' & 'TECHNICAL CO-SPONSORSHIP' (Active Count = 13)**

MEETING NAME/ACRONYM	FREQUENCY/ LAST ATTENDANCE	NEXT OCCURRENCE(S)	EDS FINANCIAL SPONSORSHIP %	CO-SPONSOR(S) & FINANCIAL %
IEEE <b>Bipolar/BiCMOS</b> Circuits and Technology Meeting (BCTM) (Alternates between the east and west coasts of the U.S. and Europe)	Annual/05 = 225 3 year rotation	9/30-10/2/07 - East Coast U.S.	100%	1986 - IEEE Twin Cities Section (50%) Univ of MN (50%)
		Oct. 2008 - West Coast U.S.		
		2009 - Europe	0%	2003 - LAAS/CNRS of France 2009 - BCTM Foundation, The Netherlands
IEEE International Conference on <b>Indium Phosphide</b> and Related Materials (IPRM)	Annual/06 = 300	May 2009 - U.S.	50%	IEEE LEOS (50%)
		2007 - Japan	0%	95-04- JSAP of Japan
		2008 - Europe	50%	1993 LEOS (50%), SEE of France (50%) 1996 - ITG/VDE of Germany 2002 - JSAP (100%) 2005 & 2008 - LEOS (50%) & EDS (50%)
Intersociety Energy Conversion Engineering Conference (IECEC)	Annual/02 = 213	<i>Support Ended in 2003</i>	0%	ANS, SAE, AIAA, ASME, AIChE - Alternate each year (100%). ACS withdrew as sponsor, effective 1995
				1989 - IEEE AES (45.6%), IEEE NCAC (8.8%) 1996 - IEEE AES (17%), IEEE NCAC (1%)
IEEE International Conference on <b>Microelectronic Test Structures</b> (ICMTS)	Annual/06 = 125	2010 - Japan	0%	APEEIE
		5/24-27/08 - Europe	0%	2005 - Katholieke Univ. Leuven 2008 - EDS (100%)
		2009 - U.S.	100%	N/A
IEEE World Conference on <b>Photovoltaic</b> Energy Conversion (WCPEC)	Every 4 years/06= 1,426	2010 - Europe or Asia Joint w/ PVSC, PVSEC & PSEC	100%	1998 - European Commission 2003 - PVSC Organizing Committee 2005 - EDS (100%)
IEEE International Symposium on <b>Power Semiconductor Devices and Integrated Circuits</b> (ISPSD)	Annual/06 = 500	2010 - Asia	0%	IEE of Japan
		5/18-22/08 - U.S.	100%	N/A
		2009 - Europe	0%	1994 - Swiss Federal Inst 1997 - VDE 2000 - LAAS 2003 - UDC (80%), UK EPSRC (20%) 2006 - IEE Japan (100%)
IEEE International Symposium on <b>Semiconductor Manufacturing</b> (ISSM)	Annual/06 = 500	9/15-17/07 - U.S.	50%	1993 - 100% 1995 - Present CPMT (50%)
		2008 - Japan	0%	UCS of Japan
IEEE <b>Silicon Nanoelectronics Workshop</b> (SNW)	Annual/06 = 135	2007 - Japan	0%	JSAP of Japan
		Jun-08 - U.S.	100%	N/A



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IEEE International Conference on <b>Simulation</b> of Semiconductor Processes and Devices (SISPAD)	Annual/06 = 125	9/25-27/07 - Europe	0%	1999 - IMEC of Belgium 2001 - NCSR Demokritos of Greece 2004 - Munich Univ of Technology 2007 - Tech Univ of Vienna (100%)
		2008 - Japan	0%	JSAP of Japan
		2009 - U.S.	100%	N/A
IEEE International Workshop on <b>Statistical</b> Methodology for VLSI Design and Fabrication (IWSM)	Annual/98 = 49	<i>Workshop Discontinued 11/01/02</i>	0%	JSAP of Japan
			100%	N/A
IEEE <b>TRANSDUCERS</b> - International Conference on Solid-State Sensors, Actuators and Microsystems (TRANSDUCERS)	Biennial/07 = 1,000	2013 - Europe	0%	1995 - Foundation for Sensor and Actuator Technology of Sweden 2001 - DFG of Germany 2007 - CEA Minattec
		6/14-6/18/09 - U.S.	100%	N/A
		2011 - Asia	0%	1987 - IEE of Japan 1993 - IEE of Japan, Japan Science Foundation 1999 - N/A 2005 - KSS
IEEE International <b>Vacuum</b> Electron Sources Conference (IVESC) <i>(2 Year rotation between U.S., Europe &amp; Asia)</i>  (For 2006 occurrence, co-located with IVEC)	Biennial/06 = 400	2008 - Europe	0%	2002 - Russian Ministry of Industry (25%) Russian Fund of Fundamental Research (25%) Government of Saratov Region, Russia (25%) Enterprises of Electron Industry (15%) IEEE MTT/EDI/API/CPMT Saratov-Penza Chapter (10%)
		2010 - Asia	0%	1998 - IUJVSTA, Vacuum Society of Japan, JSPS 2004 - CIE China (100%)
		2012 - U.S.	100%	N/A
IEEE International <b>Vacuum</b> Nanoelectronics Conference (IVNC) (formerly - Int'l Vac. Microelectronics Conf. - IVMC)	Annual/06 = 400	7/8-12/07 - U.S.	100%	2007 - Electron Devices Society
			0%	2001 - Univ of California
		7/13-17/08 - Europe	100%	1989 - IOP of UK 1992 - Austrian Ministry of Science and Research (50%), Vienna Tourist Board, Austria (50%) 1994 - Societe Francaise du Vide of Franceb 2002 - University of Lyon 2005 - Oxford University
			0%	1991 - JSAP of Japan 1997 - Electronic Display Industrial Research Association for Korea 2003 - JSPS 2006 - SYU - Sun Yat-sen University (95%), NSFC - Ministry of Education of China (5%)
IEEE International <b>Vacuum</b> Electronics Conference (IVEC) (Even numbered years in U.S. Odd numbered years alternate between Europe and Asia)  (For 2006 occurrence, co-located with IVESC)	Annual/06 = 400	4/22-24/08 - U.S.	100%	N/A
		2010 - Asia	100%	N/A
		2009 - Europe	0%	2001 - ESTEC of Norway 2005 - ESA of the Netherlands



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IEEE Symposium on VLSI Technology (No std. acronym)	Annual/06 = 595	2009 - Japan	0%	JSAP of Japan
		6/18-20/08 - US	100%	N/A

**TOTAL ACTIVE EDS MEETINGS**  
as of 06 July 2007

SUPPORT TYPE	COUNT
Sponsorship/Co-Sponsorship *	26
Technical Co-Sponsorship **	140
Cooperation	0
<b>Total</b>	<b>166</b>

\* Includes 13 meetings for which EDS alternates support between 'sponsorship/co-sponsorship' and 'technical co-sponsorship'

\*\* Includes 52 meetings fully/partially organized by ED Chapters

Sponsor Name	Sponsor Acronym	Sponsor Country
A.S. Popov Russin Scien. & Tech. Society for Radio Eng., Elec. & Telecom	ASPOPOV	Russia
Academy of Scientific Research & Tech.	ASRT	Egypt
ACI SIG on Design Automation	ACI SIG	India
ACM - SIGDA	ACM	USA
ACM/SIGNA	ACM/SIGNA	USA
ADERA Services	ADERA	France
Administration of Tomsk Region	ATR	Russia
Aerospace Electronic Systems Society	AES	USA
AES/AP/ED/EMB/MTT/GRS/LEO/NPS East Ukraine Joint Chapter	East UK	Ukraine
Alexandria University	AU	Egypt
All India Council	AIC	India
American Society of Mechanical Engineers	ASME	USA
American University of Beirut	AUB	Lebanon
American Vacuum Society	AVS	USA
Applied Computational Research Society	ACRS	USA
Assoc. for Promotion of Electrical, Electronic & Information Engrg.	APEEIE	Japan
ATMI Inc.	ATMI	USA
Atomic Energy Authority	AEA	Egypt
Australian Research Council Nanotechnology Network	ARCNN	Australia
BCTM2006 Foundation	BCTM	The Netherlands
Brazilian Computer Society	BCS	Brazil
Brazilian Microelectronics Society	Brazil	Brazil
Brazilian Research Funding Agency	BRFA	Brazil
BSUIR	BSUIR	Ukraine
Catalan Regional Government	CRG	Spain
CESPA - CNR	CNR	Italy
Chinese Institute of Electronics	CIE	China
Chinese University of Hong Kong	CUHK	China
Chipidea Microelectronics	CM	Portugal
CINVESTAV-IPN	CINVESTAV	Mexico
CNRS, National Agency for Scientific Research	CNRS	France
Components, Packaging & Manufacturing Technology Society	CPMTS	USA
Coordinated Accelerator Research in Europe Project	CARE	Poland
CRDF (REC-006)	CRDF	Russia
Croucher Foundation	CF	China
CSIC	CSIC	Spain
Czech Noise Research Lab	CNRL	Czech Republic
DARPA	DARPA	USA
Delft Institute of Microelectronics and Submicrontechnology	DIMES	The Netherlands

Sponsor Name	Sponsor Acronym	Sponsor Country
Department of Energy	DOE	USA
Department of Microelectronics & Computer Science, Tech Univ of Lodz	UN Lodz	Poland
Device Research Conference Organization	DRC	USA
Dnepropetrovsk National University	DNU	Ukraine
Dod of the USA	DoD	USA
Ecole Mohammadia	ECOLE	Morocco
ECS Electronic Division	ECSED	USA
ED Beijing	ED Beijing	China
ED Hong Kong	ED Hong	Hong Kong
ED Israel Chapter	ED Israel	Israel
ED Kansai Chapter	ED Kansai	Japan
ED Malaysia - IEEE ED Malaysia Chapter	Malaysia	Malaysia
ED Mexico Chapter	ED Mexico	Mexico
ED Republic of Georgia	ED Georgia	Ukraine
ED Spain Chapter	ED Spain	Spain
ED Taipei Chapter	ED Taipei	Taiwan
ED West Ukraine Chapter	ED Ukraine	Ukraine
Egyptian Academy of Scientific Research & Technology	EASRT	Egypt
Electrochemical Society	ECS	USA
Electron Devices Society	EDS	USA
Electronic Industries Association/JEDEC	EIA/JEDEC	USA
Electronics Industry Association	EIA	USA
Electronics Society, IEICE, Japan	IEICE	Japan
ENEA CR Portia	ENEA	Italy
Enterprises of Electron Industry of Russian & Other countries	EEIROC	Russia
EPSRC	EPSRC	United Kingdom
ESD Association	ESD	USA
ESTEC Conference Bureau	ESTEC	Norway
EU Growth Network aSiNet	EUNA	Portugal
European Commission	IST	France
European Commission Project "SINANO"	SINANO	Ukraine
European Growth Program of the 5th Framework Program	EGP	Slovak Republic
European Microwave Association	EuMA	USA
European Space Agency	ESA	The Netherlands
European Union	EU	Slovak Republic
Faculty of Elec. Eng., Nis	FEE Nis	Serbia & Montenegro
Faculty of Electronic Enigenering Univ of Nis	Nis	Yugoslavia
Federal Agency for Atomic Energy of the Russian Federation	FAAERF	Russia
FhG IIS-B	FhG	Germany
Florida West Coast Section	FWC	USA
Fraunhofer Institute for Applied Solid State Physics Freiburg	FIASSPF	Switzerland
French Ministries of Education and Defense	FMED	France
Fudan University	Fudan	China
Gallium Arsenide Application Symposium Committee	GAAS	USA
German National Science Foundation	DFG	Germany
German Research Society	DFC	Germany
Government of Saratove Region, Russia	GSRR	Russia
Hellas (Forth) of Greece	HELLAS	Greece
HITEN	HITEN	Norway
IEE of Japan	IEE of Jap	Japan
IEE of Korea	IEEK	Korea
IEEE Antennas & Propagation Society	APS	USA
IEEE Benelux Chapter	Benelux	France
IEEE Boise Section	Boise Sect	USA
IEEE Bombay Section	IBS	India
IEEE Broadcast Technology Society	BTS	USA

Sponsor Name	Sponsor Acronym	Sponsor Country
IEEE Byisk Student Branch Chapter	Byisk	Russia
IEEE CAS/ED North Jersey Chapter	CAS/ED NJ	USA
IEEE CASS	CASS	USA
IEEE Circuits and Systems	CAS	USA
IEEE Communications Society	ComSoc	USA
IEEE Computer Society	CS	USA
IEEE Council on Electronic Design Automation	CEDA	USA
IEEE East Ukraine Joint Chapter	E Ukraine	Ukraine
IEEE ED Boise Chapter	ED Boise	USA
IEEE ED Malaysia Section	ED Malaysi	Malaysia
IEEE ED Society	ED	USA
IEEE ED/MTT France Chapter	France	France
IEEE ED/SSC Seoul Chapter	Seoul	Korea
IEEE ED/SSC Serbia & Montenegro	ED Serbia	Serbia & Montenegro
IEEE Electromagnetic Society	ES	USA
IEEE Japan Council	ED Japan	Japan
IEEE MTT/ED/AP/CPMT/Saratov-Penza Chapter	IEEE	Russia
IEEE Nanotechnology Council	NANO	USA
IEEE New Technology Directions Committee	TAB NTDC	USA
IEEE Novosibirsk Chapter	Novosibirs	Russia
IEEE Princeton Section	Princeton	USA
IEEE Region 5	IEEE R5	USA
IEEE Rochester Section	Rochester	USA
IEEE Sensors Council	Sensors	USA
IEEE Serbia & Montenegro	Serbia	Serbia & Montenegro
IEEE Siberian Section	SiberiaSec	Russia
IEEE Singapore Section	Singapore	Singapore
IEEE TAB New Technology Directions Committee	NTDC	USA
IEEE-USA	IEEE USA	USA
IEEE-Venezuela CAS/ED/PEL Joint Chapter	Venezuela	Venezuela
IEIIT-CNR	IEIIT	Italy
IM Austria	IMA	Austria
IMEC	IMEC	Belgium
Indian Statistical Institute	ISI	India
Industrial Electronics Society	IES	USA
Industrial Technology Research Institute Ministry of Economic Affairs, ROC	ITRI	Taiwan
Insittuto Nacional de Astrofisica	INAOE	Mexico
Institute for Problems of Electrophysics	IPE	Russia
Institute of Applied Problems of Mechanics and Mathematics	IAPMM	Ukraine
Institute of Electrical Engineering SAS	IEE SAS	Slovak Republic
Institute of Semiconductor, Chinese Academy of Sciences	ISCAS	China
INTAS	INTAS	Ukraine
Intelligent Transportation Systems Conference	ITSC	USA
Interface-MFG Co.	MFG	Russia
International Microelectronics & Packaging Society	IMAPS	USA
International Union of Pure & Applied Physics	IUPAP	USA
Int'l Conf. On Electron, Ion & Photon Beam Tec & Nanofabricatio	EIPBN	USA
IRE of National Academy of Science	IRE	Ukraine
ISP SB RAS	ISP SB RAS	Russia
ISQED Organizing Committee	ISQED	USA
Istituto Superiore Mario Boella	ISMB	Italy
Japan Society for Promotion of Science	JSPS	Japan
Japan Society of Applied Physics	JSAP	Japan
JEDEC Solid State Technology Association	JEDEC	USA
King Fahd University of Petroleum and Minerals	KFUPM	Saudi Arabia
Korean Sensors Society	KSS	Korea
LAAS/CNRS	LAAS/CNRS	France

<b>Sponsor Name</b>	<b>Sponsor Acronym</b>	<b>Sponsor Country</b>
Lasers & Electro-Optics Society	LEOS	USA
Lien-Ho Foundation	LHF	Taiwan
Lviv Polytechnic National University	LPNU	Ukraine
Lviv Regional Directorate of VAT UKRTELECOM	LRDVU	Ukraine
Lviv Regional Division of Manufactures & Entrepreneurs Union	LRDMEU	Ukraine
Maria Curie-Sklodowska University	MCSU	Poland
Materials Research Society	MRS	USA
Meisei University, GESC	Meisei	Japan
Mexican Government (SEP-CONACyT)	Mex Gov't	Mexico
Micron Foundation	Micron	USA
Microwave Theory & Techniques Society	MTT	USA
Minatec (CEA)	CEA	France







